



Material Content Data Sheet



Sales Product Name	TLE6711GL			Issued	19. July 2018			
MA#	MA000950474							
Package	PG-DSO-20-66			Weight*	486.80 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.583	1.15	1.15	11468	11468
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6377	
wire	non noble metal	copper	7440-50-8	126.041	25.89	26.57	258919	265695
	non noble metal	copper	7440-50-8	0.250	0.05	0.05	514	514
	encapsulation	organic material	carbon black	1333-86-4	0.690	0.14		1417
encapsulation	plastics	epoxy resin	-	31.737	6.52		65196	
	inorganic material	silicondioxide	60676-86-0	312.545	64.21	70.87	642041	708654
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5641	5641
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3331	3331
glue	plastics	epoxy resin	-	0.572	0.12		1174	
	noble metal	silver	7440-22-4	1.715	0.35	0.47	3523	4697
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com